SHEET PEELING APPARATUS AND PEELING METHOD

ABSTRACT

There is provided a sheet peeling apparatus and a peeling method using a plurality of peeling units capable of performing peeling off operation under optimum condition in accordance with the material, thickness or the like of a protective sheet. A sheet peeling apparatus 10 for peeling off a sheet S stuck on the surface of a semiconductor wafer W by using an adhesive tape T of a width narrower than that of the sheet S, which is equipped with a peeling head 15 (second peeling unit) for peeling off the sheet S by pulling the adhesive tape T in an obtuse angled direction in a state stuck to the end portion of the sheet; and first and second rollers 21, 22 (first peeling unit) for peeling off the sheet S by pulling the adhesive tape T in the substantially right angle or acute angle direction in a state stuck with the adhesive tape T in the direction across the sheet S. Either one of the peeling units are selectively used in accordance with the type of the sheet S.

FIGURE 13